

7900 Duo

Specifications:

Work Piece	Max. Size	Inch	6" x 6"	8" x 8"
X Axis	Cutting range	mm	410	
	Max. speed	mm/sec	600	
	Drive	Ball bearing lead screw	-	
		Air bearing slide	-	
Y1 / Y2 Axis	Cutting range	mm	160	200
	Resolution	µm	0.2	
	Cumulative accuracy	µm	1.5	
	Index accuracy	µm	2.0	
	Control Drive	Linear encoder	-	
		Ball bearing lead screw	-	
Z1 / Z2 Axis	Max. stroke	mm	25	
	Resolution	µm	0.2	
	Accuracy	µm	2.0	
	Repeatability	µm	1.0	
	Drive	Ball bearing lead screw	-	
Φ Axis	Max. rotation	Deg.	350	
	Accuracy	Arc-sec	4	
	Repeatability	Arc-sec	4	
	Drive	Closed loop direct drive	-	
Spindle	Two facing spindles		-	
	Output power	KW	1.2	
	Max. speed	RPM	60,000	
	Rated torque	Nm	0.25	
Illumination	Vertical + Oblique	High brightness LED	-	
Vision System	Digital camera	Fire-Wire link	-	
Utilities	Power supply	Single phase 50/60 Hz	220-240 VAC	
	Air consumption	L/min	260	
	Air pressure	Bar	5.5	
	Cutting water ¹	L/min	3	
	Spindle water ¹	L/min	1.1	
Dimensions	W x D x H	mm	875 x 975 x 1,450	
	Weight	Kg	900	
Features	Automatic alignment		-	
	Automatic Kerf inspection		-	
	Automatic Y offset correction		-	

¹ per spindle

Environmental Requirements:

Room Temperature: 25° C ± 5° C (77° F ± 9° F), Humidity: Less than 70% relative humidity (non-condensing)

Floor must be vibration free

Note: Specifications are subject to change without notice.



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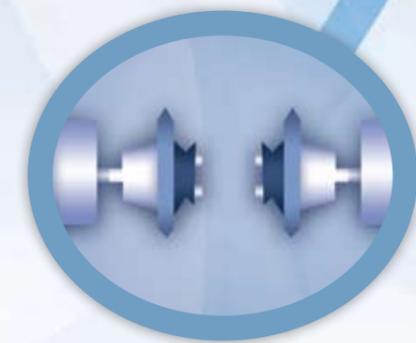
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Taking your productivity to the edge

7900 Duo



- Two Facing Spindles
- Automation
- High Accuracy
- Small Footprint
- Easy to Use



ADT = Dicing
Advanced Dicing Technologies

Taking your productivity to the edge

Double your productivity with the 7900 Duo Dicing Saw

Setting new industry standards for productivity, affordability, automation, and ease of use

Productivity

The 7900 Duo Dicing Saw is configured with two facing spindles that simultaneously dice the wafers, doubling productivity. The dicing saw is fitted with a front mount spindle eliminating the thermal effect that causes cut misplacement, resulting in increased yield.

Affordability

The system's small footprint, combined with high throughput and automation, results in reduced expenses and lowers the cost of ownership (COO), consequently delivering lower cost per die.

Automation

The powerful automated vision system aligns the wafers and provides Y offset correction and Kerf check to ensure maximum precision.

Ease of Use

The system is equipped with a 17" touch screen and easy to use GUI system for intuitive and efficient programming, set up and operation.

Ideal for LEDs, Image sensors, discrete devices, RFIDs, SAW devices, MEMS, and other products that require long cut cycle time.

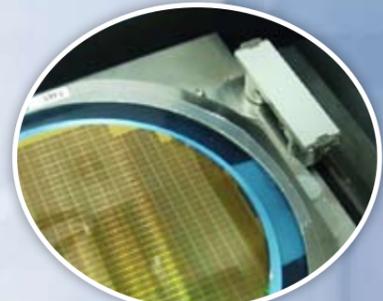


**x2
UPH**

Highly accurate system delivers low cost, high performance

Advantages

- Two facing spindles enable simultaneous dicing
- Low vibration platform
- Fast automatic alignment and cut positioning increase throughput
- Small footprint reduces cost of ownership
- Automatic Kerf inspection increases yield
- Automatic Y offset correction ensures maximum precision
- Tape surface detection ensures consistent cut quality
- Touch screen user interface



Dressing station

Options

Broken wafer recognition

enables programming of broken wafers within seconds

Tape surface detection

maintains cut depth into the dicing tape to ensure consistent cut quality on rear of wafer

Advanced multi magnification vision system

provides fast and accurate alignment of wafers for maximum throughput

High power spindle for hard and thick applications

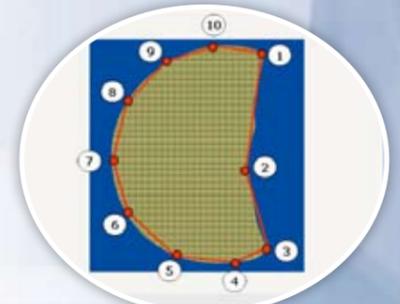
high power spindle up to 2.4 KW supporting 2"-3" O.D. blades

Customized chucks

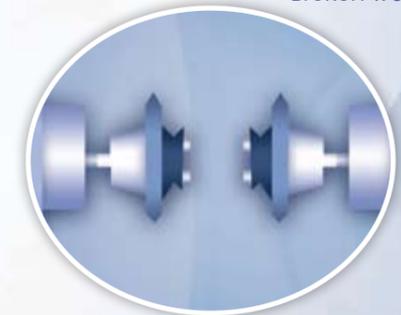
Any size and shape per customer request; standard sizes 6"-8"

Dressing station

Provides fast and efficient way to re-shape and clean the blades for new diamond exposure and clogging prevention



Broken wafer recognition



7900